

ABSTRACT OF THE DISCLOSURE

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A method of making a chip resistor is provided. According to this method, an aggregate board is first prepared which includes a first region and a second region which are spaced from each other via an excess portion. Then, a conductor pattern is formed which extends to bridge the first region and the second region. Subsequently, a resistor element is formed in each of the first region and the second region for connection to the conductor pattern. Then, the aggregate board is cut at the excess portion. The conductor pattern includes a thinner-walled portion extending across the excess portion and a thicker-walled portion connected to the thinner-walled portion and spaced from the excess portion.

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